

# Intel® Xeon Phi<sup>TM</sup> Processor Update

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## THANK YOU -- Intel® HPC Developer Conference Nov'17

Technical Content: Building Stickiness, Exposing Benefits, Sharing Industry Open Standards & Best Practice



#### **Key Topics:**

- Systems
- Enterprise
- Artificial Intelligence
- Parallel Programming
- Visualization Development
- High Productivity Languages



225+ Speakers 71% non-Intel

80 Technical Lectures (30 minute)





15 Hands-on Tutorials (90 minute)

~40 Poster Sessions





**Social Media** (follow

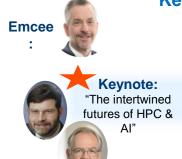








**Keynote, Panelist, Plenaries: Demonstrate Intel's Commitment to the Future** 



**Industry Panel:** "New Paradigm in Computing: What **Should Developers** Know?"

> Day 1 Plenary: "Gravitational waves: the role of computing in opening a new field of astronomy"

Day 2 Plenary: "Deep Learning for Science"



Closing Plenary: "Leading the evolution of compute: Neuromorphic and Quantum computing"







## Intel® Xeon Phi™ Processor Top500 Listings

November 2017 Top500 List<sup>1</sup> has 14 Intel Xeon Phi deployments – over 80.9 PetaFlops

#### Nine listings in Top50:



#7: Trinity (DOE/NNSA/LANL/SNL, USA); Cray XC40 – 14.1 PFs



#8: Cori (DOE/SC/LBNL/NERSC, USA); Cray XC40 - 14.0 PFs



#9: Oakforest-PACS (JCAHPC, Japan); Fujitsu CX1640 M1 – 13.5 PFs



#12: Stampede2 (TACC, USA); DellEMC PowerEdge C6320P/C6420 – 8.3 PFs



CINECA #14: Marconi (CINECA, Italy); Lenovo SD530 – 7.5 PFs



#18: Theta (DOE/SC/Argonne National Laboratory, USA); Cray XC40 – 5.9 PFs



#23: Tera-1000-2-Part 1 (CEA, France); Bull Sequana X1000 – 5.0 PFs



#32: Onyx (ERDC DSRC, USA); Cray XC40 – 3.4 PFs



#41: Camphor 2 (ACCMS, Kyoto University, Japan); Cray XC40 – 3.1 PFs



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### Roadmap Updates



- Knights Landing: In production and seeing increased adoption.
- Knights Mill: In production and systems will be available later this year.
- Knights Hill: Intel re-targeted investments in the "Knights Hill" product as we continue to focus on achieving exascale class computing as soon as feasible

## Roadmap Goals Moving Forward



Hasten Pace Of Architectural Innovation And Increase Cadence Of New Products

Deliver Improved, Real World Application Performance

Single Platform Scalable to Multiple Workloads

– Mod/Sim, AI (Machine & Deep Learning),

Analytics → On-prem and in the Cloud



#### **HPC Trends**



**Exascale Computing** 

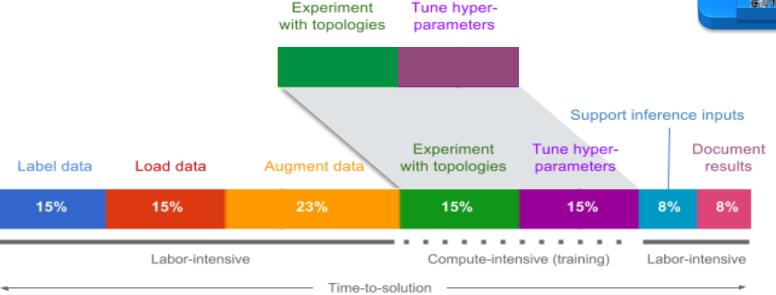


**Artificial Intelligence** 



# Dev Cycle & Time-to-Solution





30% of the DL dev cycle involves DL training 70% of the DL dev cycle is labor-intensive

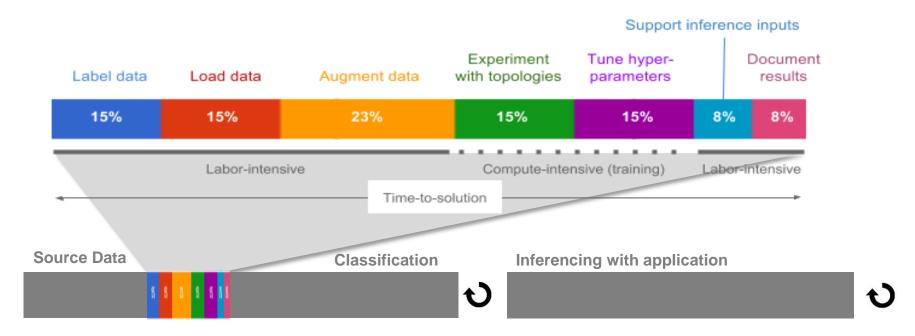


# Dev Cycle & Time-to-Solution



DL training is a fraction of time to get to solution

Time to solution is not data scientist time; it is infrastructure deployment time





#### Workflow Convergence

## → Simulation, Data Analytics and Al



#### Our customers are telling us HPC is changing......

 Clear evidence → ECP must treat Mod/Sim, AI, and Analytics as first class citizens (hardware & software)

Al has become a major consumer of computing cycles and it is expected to grow

- Compute deployment both at edge and in large cloud
- Will drive economies in fabric, compute with a large focus on power and perf/W

#### Convergence is happening in many areas

Cloud management, development tools/environments,
 Fabric architectures, and Frameworks/topologies

